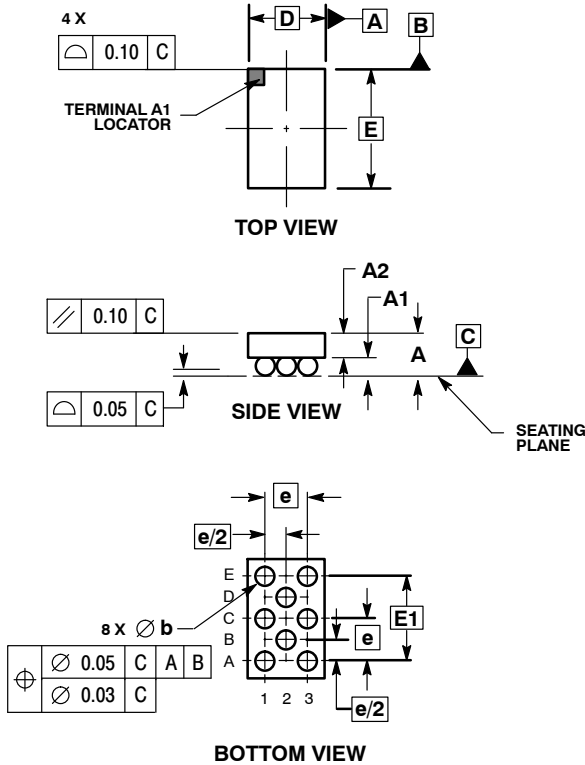




SCALE 4:1

8 PIN FLIP-CHIP
CASE 499AM
ISSUE 0

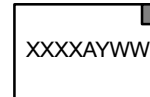
DATE 17 FEB 2005



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.700
A1	0.210	0.270
A2	0.380	0.430
D	1.270 BSC	
E	1.970 BSC	
b	0.290	0.340
e	0.700 BSC	
E1	1.400 BSC	

GENERIC MARKING DIAGRAM*



- XXXX = Specific Device Code
- A = Assembly Location
- Y = Year
- WW = Work Week
- G or ■ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking.
Pb-Free indicator, "G" or microdot "■", may or may not be present.

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DESCRIPTION:	8 PIN FLIP-CHIP, 1.970*1.270,, 0.700 LEAD PITCH	PAGE 1 OF 1

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